12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20180925002.1
Qualification of TI Malaysia as an additional Assembly Site for select devices
Change Notification / Sample Request

Date: October 05, 2018
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,
PCN Team
SC Business Services

PCN Number:	20180925002.1	**PCN Date:**	Oct. 5, 2018
Title:	Qualification of TI Malaysia as an additional Assembly Site for select devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Jan. 5, 2019	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification TI Malaysia as Additional Assembly Site for select devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City
Microchip Technology	ALP	THA	Chachoengsao
TI Malaysia	MLA	MYS	Kuala Lumpur

Material Differences:

Group 1 Device:

	Microchip Technology	TI Malaysia
Mount Compound	142010008	4147858
Mold compound	141002081	4211880
Lead finish	Matte Sn	NiPdAu

Group 2 Device:

	Microchip Technology	TI Malaysia
Mount Compound	142010008	4147858
Mold compound	141002081	4211880

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change.

Changes to product identification resulting from this PCN:

Assembly Site		
Microchip Technology	Assembly Site Origin (22L)	ASO: ALP
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
Pb G4
MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Group 1 Product Affected:

UC2875N	UC3875N	UC3876N

Group 2 Product Affected:

UC2638N	UC3638N	UC3879N	UCC38502N
UC2855BN	UC3638NG4	UCC28500N	UCC38502NG4
UC2875NG4	UC3855BN	UCC2895N	UCC3895N
UC2879N	UC3855BNG4	UCC38500N	UCC3895NG4
UC2879NG4	UC3875NG4	UCC38501N	

Qualification Report

MMT Offload Qualification for PDIP 20N devices

Approve Date 25-May-2018

Product Attributes

Attributes	Qual Device: UC3875N	Qual Device: UCC38501N	QBS Package Reference: SN74HCT540N	QBS Package Reference: TPA3122D2N
Assembly Site	MLA	MLA	MLA	MLA
Package Family	PDIP	PDIP	PDIP	PDIP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	SFAB	SFAB	SFAB	UMC FAB8AB
Wafer Fab Process	JI_PWR2	IMP-PWR2	74HC-NONEPI	LBC5X

- QBS: Qual By Similarity
- Qual Devices UC3875N and UCC38501N are qualified at Not Classified

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UC3875N	Qual Device: UCC38501N	QBS Package Reference: SN74HCT540N	QBS Package Reference: TPA3122D2N
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
FLAM	Flammability (UL 94V-0)	-	-	-	3/15/0	-

Type	Test Name / Condition	Duration	Qual Device: UC3875N	Qual Device: UCC38501N	QBS Package Reference: SN74HCT540N	QBS Package Reference: TPA3122D2N
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	3/231/0	3/231/0	3/231/0
LI	Lead Fatigue	Leads	-	-	3/45/0	3/45/0
LI	Lead Pull to Destruction	Leads	-	-	3/180/0	3/180/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass
PKG	Lead Finish Adhesion	Leads	-	-	2/30/0	3/45/0
SD	Solderability	8 Hours Steam Age	3/30/0	3/30/0	3/66/0	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com